

# FOD814 Series, FOD817 Series 4-Pin High Operating Temperature Phototransistor Optocouplers

## Features

- AC input response (FOD814 only)
- Applicable to Pb-free IR reflow soldering
- Compact 4-pin package
- Current transfer ratio in selected groups:
 

|                  |                   |
|------------------|-------------------|
| FOD814: 20–300%  | FOD817: 50–600%   |
| FOD814A: 50–150% | FOD817A: 80–160%  |
|                  | FOD817B: 130–260% |
|                  | FOD817C: 200–400% |
|                  | FOD817D: 300–600% |
- C-UL, UL and VDE approved
- High input-output isolation voltage of 5000Vrms
- Minimum  $BV_{CEO}$  of 70V guaranteed
- Higher operating temperatures (versus H11AXXX counterparts)

## Applications

### FOD814 Series

- AC line monitor
- Unknown polarity DC sensor
- Telephone line interface

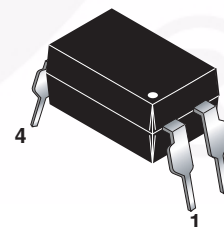
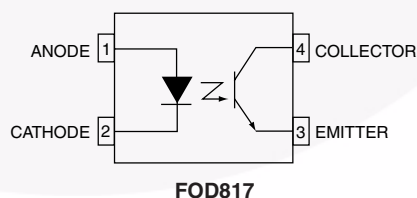
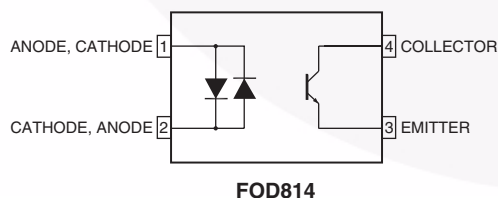
### FOD817 Series

- Power supply regulators
- Digital logic inputs
- Microprocessor inputs

## Description

The FOD814 consists of two gallium arsenide infrared emitting diodes, connected in inverse parallel, driving a silicon phototransistor output in a 4-pin dual in-line package. The FOD817 Series consists of a gallium arsenide infrared emitting diode driving a silicon phototransistor in a 4-pin dual in-line package.

## Functional Block Diagram



**Absolute Maximum Ratings** ( $T_A = 25^\circ\text{C}$  Unless otherwise specified.)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol           | Parameter                                        | Value          |             | Units |
|------------------|--------------------------------------------------|----------------|-------------|-------|
|                  |                                                  | FOD814         | FOD817      |       |
| TOTAL DEVICE     |                                                  |                |             |       |
| T <sub>STG</sub> | Storage Temperature                              | -55 to +150    |             | °C    |
| T <sub>OPR</sub> | Operating Temperature                            | -55 to +105    | -55 to +110 | °C    |
| T <sub>SOL</sub> | Lead Solder Temperature                          | 260 for 10 sec |             | °C    |
| T <sub>J</sub>   | Junction Temperature                             | 125 Max.       |             | °C    |
| θ <sub>JC</sub>  | Junction-to-Case Thermal Resistance              | 210            |             | °C/W  |
| P <sub>TOT</sub> | Total Power Dissipation                          | 200            |             | mW    |
| EMITTER          |                                                  |                |             |       |
| I <sub>F</sub>   | Continuous Forward Current                       | ±50            | 50          | mA    |
| V <sub>R</sub>   | Reverse Voltage                                  |                | 6           |       |
| P <sub>D</sub>   | Power Dissipation<br>Derate above 100°C          | 70             |             | mW    |
|                  |                                                  | 1.7            |             | mW/°C |
| DETECTOR         |                                                  |                |             |       |
| V <sub>CEO</sub> | Collector-Emitter Voltage                        | 70             |             | V     |
| V <sub>ECO</sub> | Emitter-Collector Voltage                        | 6              |             | V     |
| I <sub>C</sub>   | Continuous Collector Current                     | 50             |             | mA    |
| P <sub>C</sub>   | Collector Power Dissipation<br>Derate above 90°C | 150            |             | mW    |
|                  |                                                  | 2.9            |             | mW/°C |

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  Unless otherwise specified.)**Individual Component Characteristics**

| Symbol            | Parameter                           | Device | Test Conditions                            | Min. | Typ.* | Max. | Unit |
|-------------------|-------------------------------------|--------|--------------------------------------------|------|-------|------|------|
| EMITTER           |                                     |        |                                            |      |       |      |      |
| V <sub>F</sub>    | Forward Voltage                     | FOD814 | I <sub>F</sub> = ±20mA                     |      | 1.2   | 1.4  | V    |
|                   |                                     | FOD817 | I <sub>F</sub> = 20mA                      |      | 1.2   | 1.4  |      |
| I <sub>R</sub>    | Reverse Leakage Current             | FOD817 | V <sub>R</sub> = 4.0V                      |      |       | 10   | μA   |
| C <sub>t</sub>    | Terminal Capacitance                | FOD814 | V = 0, f = 1kHz                            |      | 50    | 250  | pF   |
|                   |                                     | FOD817 | V = 0, f = 1kHz                            |      | 30    | 250  |      |
| DETECTOR          |                                     |        |                                            |      |       |      |      |
| I <sub>CEO</sub>  | Collector Dark Current              | FOD814 | V <sub>CE</sub> = 20V, I <sub>F</sub> = 0  |      |       | 100  | nA   |
|                   |                                     | FOD817 | V <sub>CE</sub> = 20V, I <sub>F</sub> = 0  |      |       | 100  |      |
| BV <sub>CEO</sub> | Collector-Emitter Breakdown Voltage | FOD814 | I <sub>C</sub> = 0.1mA, I <sub>F</sub> = 0 | 70   |       |      | V    |
|                   |                                     | FOD817 | I <sub>C</sub> = 0.1mA, I <sub>F</sub> = 0 | 70   |       |      |      |
| BV <sub>ECO</sub> | Emitter-Collector Breakdown Voltage | FOD814 | I <sub>E</sub> = 10μA, I <sub>F</sub> = 0  | 6    |       |      | V    |
|                   |                                     | FOD817 | I <sub>E</sub> = 10μA, I <sub>F</sub> = 0  | 6    |       |      |      |

**DC Transfer Characteristics**

| Symbol        | DC Characteristic                    | Device  | Test Conditions                                  | Min. | Typ.* | Max. | Unit |
|---------------|--------------------------------------|---------|--------------------------------------------------|------|-------|------|------|
| CTR           | Current Transfer Ratio               | FOD814  | $I_F = \pm 1\text{mA}, V_{CE} = 5\text{V}^{(1)}$ | 20   |       | 300  | %    |
|               |                                      | FOD814A |                                                  | 50   |       | 150  |      |
|               |                                      | FOD817  | $I_F = 5\text{mA}, V_{CE} = 5\text{V}^{(1)}$     | 50   |       | 600  |      |
|               |                                      | FOD817A |                                                  | 80   |       | 160  |      |
|               |                                      | FOD817B |                                                  | 130  |       | 260  |      |
|               |                                      | FOD817C |                                                  | 200  |       | 400  |      |
|               |                                      | FOD817D |                                                  | 300  |       | 600  |      |
| $V_{CE(sat)}$ | Collector-Emitter Saturation Voltage | FOD814  | $I_F = \pm 20\text{mA}, I_C = 1\text{mA}$        |      | 0.1   | 0.2  | V    |
|               |                                      | FOD817  | $I_F = 20\text{mA}, I_C = 1\text{mA}$            |      | 0.1   | 0.2  |      |

**AC Transfer Characteristics**

| Symbol | AC Characteristic    | Device         | Test Conditions                                                      | Min. | Typ.* | Max. | Unit          |
|--------|----------------------|----------------|----------------------------------------------------------------------|------|-------|------|---------------|
| $f_C$  | Cut-Off Frequency    | FOD814         | $V_{CE} = 5\text{V}, I_C = 2\text{mA}, R_L = 100\Omega, -3\text{dB}$ | 15   | 80    |      | kHz           |
| $t_r$  | Response Time (Rise) | FOD814, FOD817 | $V_{CE} = 2\text{V}, I_C = 2\text{mA}, R_L = 100\Omega^{(2)}$        |      | 4     | 18   | $\mu\text{s}$ |
| $t_f$  | Response Time (Fall) | FOD814, FOD817 |                                                                      |      | 3     | 18   | $\mu\text{s}$ |

\*Typical values at  $T_A = 25^\circ\text{C}$

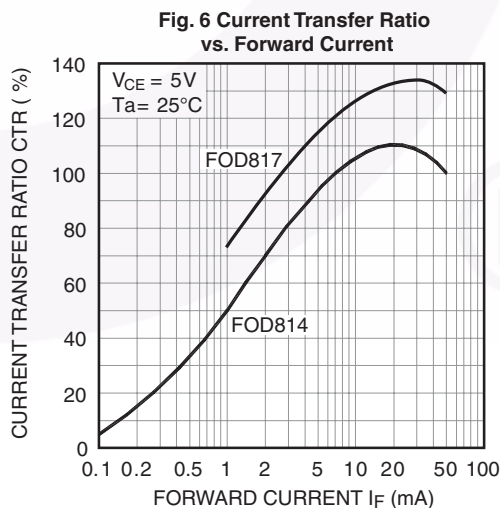
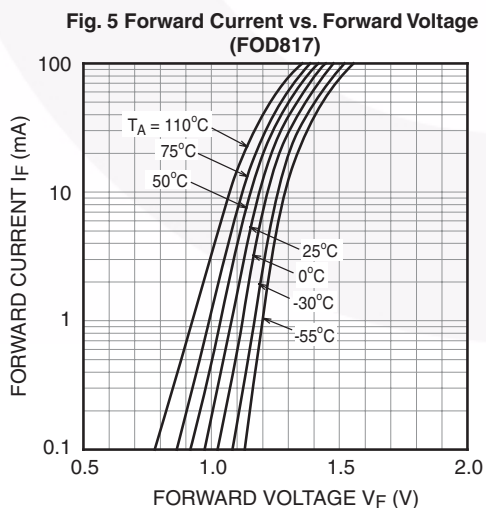
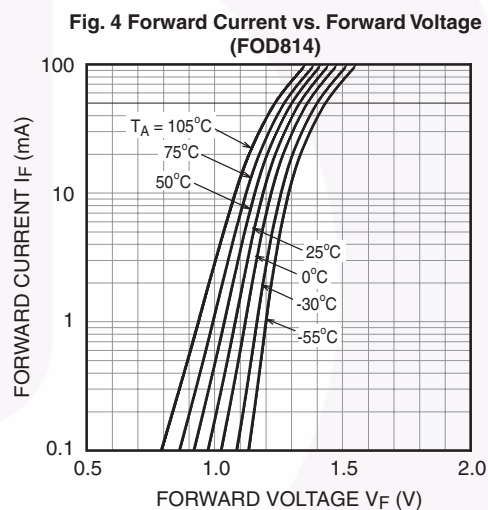
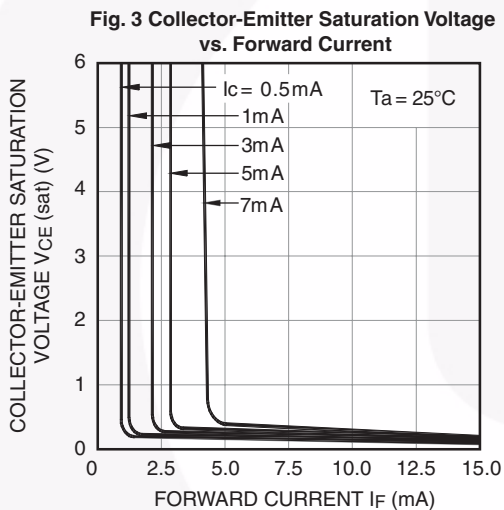
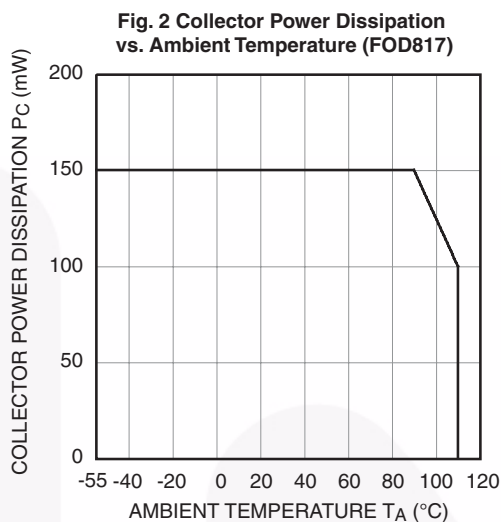
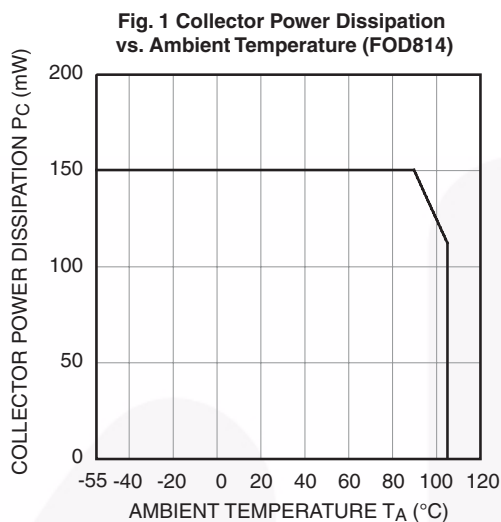
**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  Unless otherwise specified.) (Continued)**Isolation Characteristics**

| Symbol           | Characteristic                                | Device            | Test Conditions                                                                 | Min.               | Typ.*              | Max. | Units    |
|------------------|-----------------------------------------------|-------------------|---------------------------------------------------------------------------------|--------------------|--------------------|------|----------|
| $V_{\text{ISO}}$ | Input-Output Isolation Voltage <sup>(3)</sup> | FOD814,<br>FOD817 | $f = 60\text{Hz}$ , $t = 1 \text{ min}$ ,<br>$I_{\text{I-O}} \leq 2\mu\text{A}$ | 5000               |                    |      | Vac(rms) |
| $R_{\text{ISO}}$ | Isolation Resistance                          | FOD814,<br>FOD817 | $V_{\text{I-O}} = 500\text{VDC}$                                                | $5 \times 10^{10}$ | $1 \times 10^{11}$ |      | $\Omega$ |
| $C_{\text{ISO}}$ | Isolation Capacitance                         | FOD814,<br>FOD817 | $V_{\text{I-O}} = 0$ , $f = 1 \text{ MHz}$                                      |                    | 0.6                | 1.0  | pf       |

\*Typical values at  $T_A = 25^\circ\text{C}$ **Notes:**

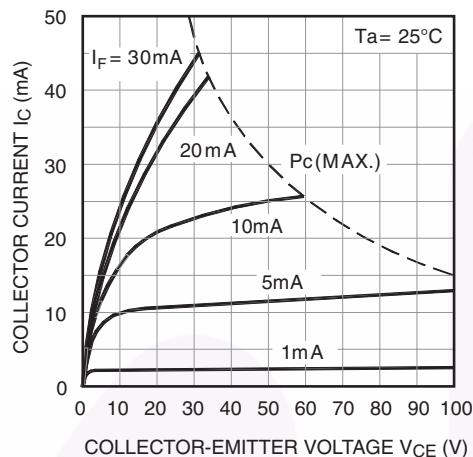
1. Current Transfer Ratio (CTR) =  $I_C/I_F \times 100\%$ .
2. For test circuit setup and waveforms, refer to page 7.
3. For this test, Pins 1 and 2 are common, and Pins 3 and 4 are common.

## Typical Electrical/Optical Characteristics ( $T_A = 25^\circ\text{C}$ Unless otherwise specified.)

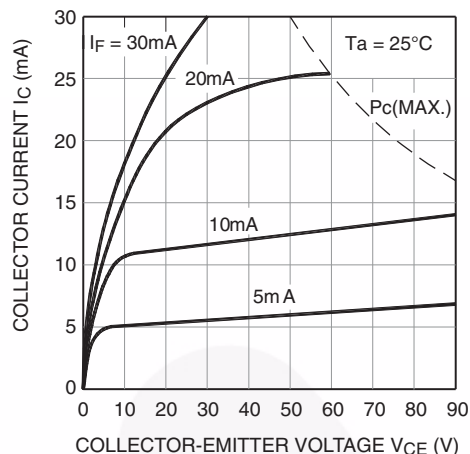


## Typical Electrical/Optical Characteristics (Continued) ( $T_A = 25^\circ\text{C}$ Unless otherwise specified.)

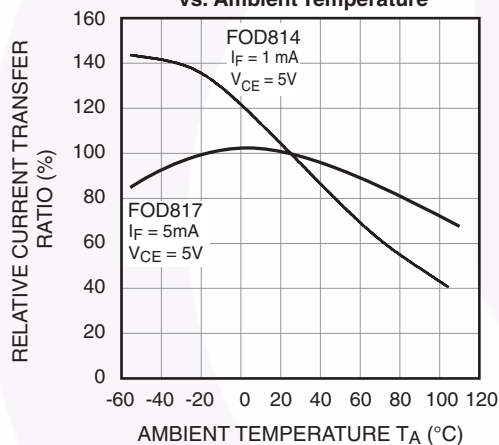
**Fig. 7 Collector Current vs. Collector-Emitter Voltage (FOD814)**



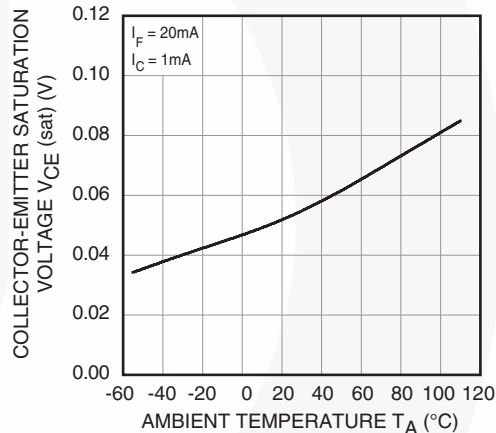
**Fig. 8 Collector Current vs. Collector-Emitter Voltage (FOD817)**



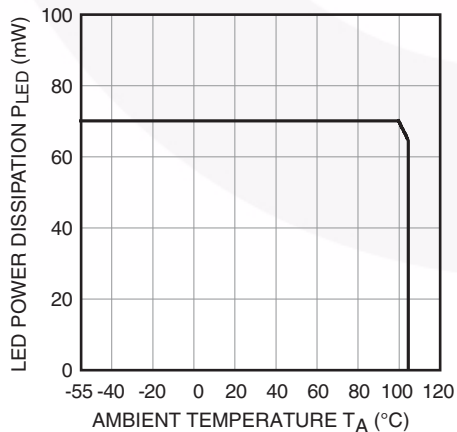
**Fig. 9 Relative Current Transfer Ratio vs. Ambient Temperature**



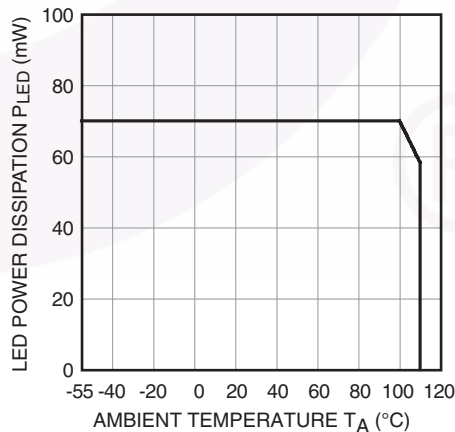
**Fig. 10 Collector-Emitter Saturation Voltage vs. Ambient Temperature**



**Fig. 11 LED Power Dissipation vs. Ambient Temperature (FOD814)**

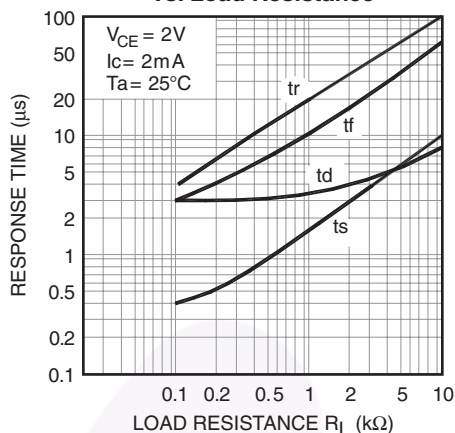


**Fig. 12 LED Power Dissipation vs. Ambient Temperature (FOD817)**

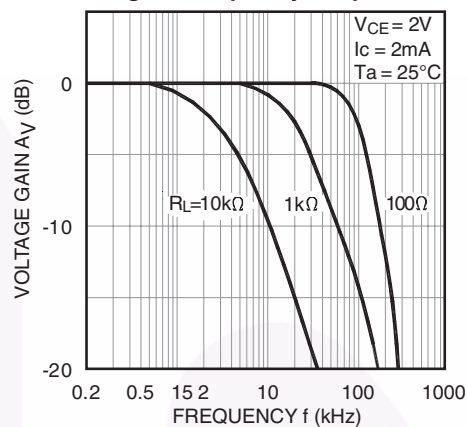


## Typical Electrical/Optical Characteristics (Continued) ( $T_A = 25^\circ\text{C}$ Unless otherwise specified.)

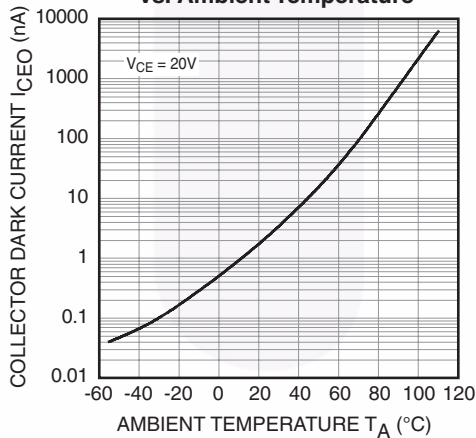
**Fig. 13 Response Time vs. Load Resistance**



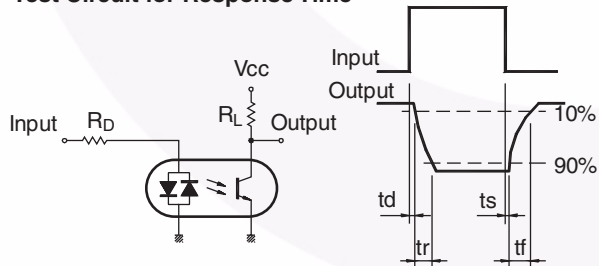
**Fig. 14 Frequency Response**



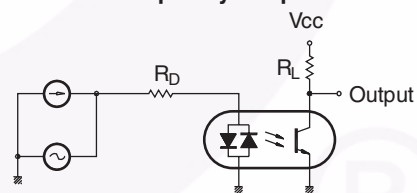
**Fig. 15 Collector Dark Current vs. Ambient Temperature**



**Test Circuit for Response Time**

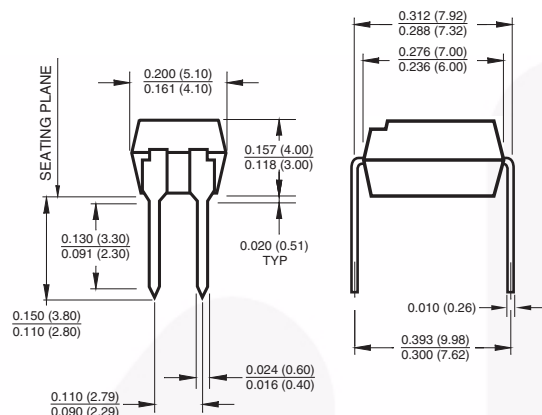


**Test Circuit for Frequency Response**

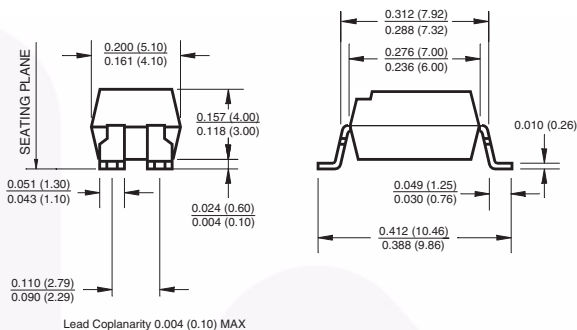


## Package Dimensions

### Through Hole

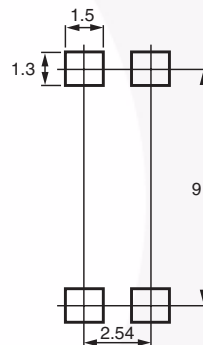
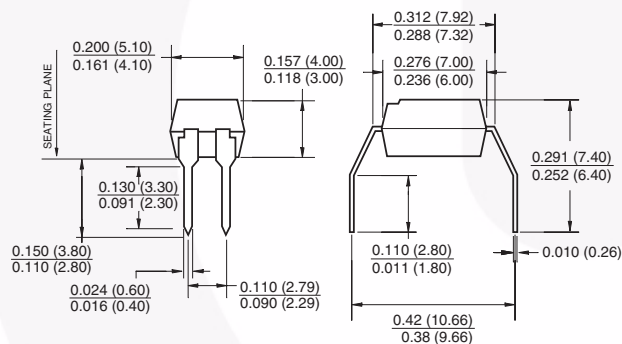


### Surface Mount



### Surface Mount (Footprint Dimensions)

#### 0.4" Lead Spacing



#### Note:

All dimensions are in inches (millimeters)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

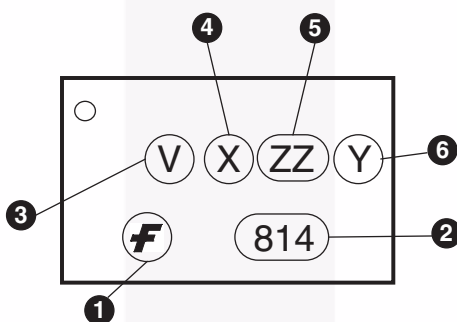
Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>

## Ordering Information

| Option | Part Number Example | Description                              |
|--------|---------------------|------------------------------------------|
| S      | FOD814S             | Surface Mount Lead Bend                  |
| SD     | FOD814SD            | Surface Mount; Tape and reel             |
| 300    | FOD814300           | VDE Approved                             |
| 300W   | FOD814300W          | VDE Approved, 0.4" Lead Spacing          |
| 3S     | FOD8143S            | VDE Approved, Surface Mount              |
| 3SD    | FOD8143SD           | VDE Approved, Surface Mount, Tape & Reel |

## Marking Information



| Definitions |                                                                                        |
|-------------|----------------------------------------------------------------------------------------|
| 1           | Fairchild logo                                                                         |
| 2           | Device number                                                                          |
| 3           | VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table) |
| 4           | One digit year code                                                                    |
| 5           | Two digit work week ranging from '01' to '53'                                          |
| 6           | Assembly package code<br>Y = Manufactured in Thailand<br>YA = Manufactured in China    |

Technical drawing of a mechanical component, showing a top view and a side view.

**Top View Dimensions:**

- Overall width:  $1.75 \pm 0.1$
- Overall height:  $W$
- Height of the central section:  $B_0$
- Width of the central section:  $A_0$
- Distance from the left edge to the center of the first hole:  $P_1$
- Distance between the centers of the first and second holes:  $P_2$
- Distance from the center of the last hole to the right edge:  $P_0$
- Radius of the circular holes:  $\varnothing 1.55 \pm 0.05$

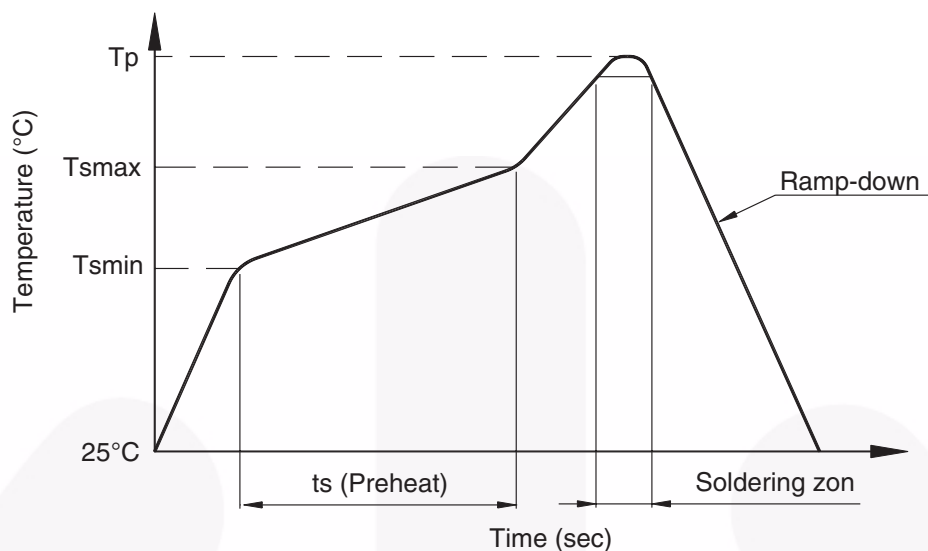
**Side View Dimensions:**

- Overall height:  $K_0$
- Distance from the top surface to the bottom of the central section:  $0.3 \pm 0.05$

All dimensions are in millimeters.

| Symbol              | Description                            | Dimensions in mm (inches)          |
|---------------------|----------------------------------------|------------------------------------|
| W                   | Tape wide                              | 16 ± 0.3 (.63)                     |
| P <sub>0</sub>      | Pitch of sprocket holes                | 4 ± 0.1 (.15)                      |
| F<br>P <sub>2</sub> | Distance of compartment                | 7.5 ± 0.1 (.295)<br>2 ± 0.1 (.079) |
| P <sub>1</sub>      | Distance of compartment to compartment | 12 ± 0.1 (.472)                    |
| A0                  | Compartment                            | 10.45 ± 0.1 (.411)                 |
| B0                  |                                        | 5.30 ± 0.1 (.209)                  |
| K0                  |                                        | 4.25 ± 0.1 (.167)                  |

### Lead Free Recommended IR Reflow Condition



| Profile Feature                                               | Pb-Sn solder assembly         | Lead Free assembly            |
|---------------------------------------------------------------|-------------------------------|-------------------------------|
| Preheat condition<br>(T <sub>sm</sub> -T <sub>max</sub> / ts) | 100°C ~ 150°C<br>60 ~ 120 sec | 150°C ~ 200°C<br>60 ~ 120 sec |
| Melt soldering zone                                           | 183°C<br>60 ~ 120 sec         | 217°C<br>30 ~ 90 sec          |
| Peak temperature (T <sub>p</sub> )                            | 240 +0/-5°C                   | 260 +0/-5°C                   |
| Ramp-down rate                                                | 6°C/sec max.                  | 6°C/sec max.                  |

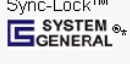
### Recommended Wave Soldering condition

| Profile Feature                    | For all solder assembly |
|------------------------------------|-------------------------|
| Peak temperature (T <sub>p</sub> ) | Max 260°C for 10 sec    |



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|                                                                                   |                                                                                   |                                                                                   |                                                                                     |
|-----------------------------------------------------------------------------------|-----------------------------------------------------------------------------------|-----------------------------------------------------------------------------------|-------------------------------------------------------------------------------------|
| AccuPower™                                                                        | FPS™                                                                              | Power-SPM™                                                                        | The Power Franchise®                                                                |
| Auto-SPM™                                                                         | F-PFS™                                                                            | PowerTrench®                                                                      | The Right Technology for Your Success™                                              |
| AX-CAP™                                                                           | FRFET®                                                                            | PowerXS™                                                                          |  |
| BitSiC®                                                                           | Global Power Resource™                                                            | Programmable Active Droop™                                                        | TinyBoost™                                                                          |
| Build it Now™                                                                     | Green FPS™                                                                        | QFET®                                                                             | TinyBuck™                                                                           |
| CorePLUS™                                                                         | Green FPS™ e-Series™                                                              | QS™                                                                               | TinyCalc™                                                                           |
| CorePOWER™                                                                        | Gmax™                                                                             | Quiet Series™                                                                     | TinyLogic®                                                                          |
| CROSSVOLT™                                                                        | GTO™                                                                              | RapidConfigure™                                                                   | TINYOPTO™                                                                           |
| CTL™                                                                              | IntelliMAX™                                                                       |  | TinyPower™                                                                          |
| Current Transfer Logic™                                                           | ISOPLANAR™                                                                        | Saving our world, 1mW/W/kV at a time™                                             | TinyPVM™                                                                            |
| DEUXPEED®                                                                         | MegaBuck™                                                                         | SignalVise™                                                                       | TinyWire™                                                                           |
| Dual Cool™                                                                        | MICROCOUPLER™                                                                     | SmartMax™                                                                         | TranSiC®                                                                            |
| EcoSPARK®                                                                         | MicroFET™                                                                         | SMART START™                                                                      | TriFault Detect™                                                                    |
| EfficientMax™                                                                     | MicroPak™                                                                         | SPM®                                                                              | TRUECURRENT®                                                                        |
| ESBCT™                                                                            | MicroPak2™                                                                        | STEALTH™                                                                          | μSerDes™                                                                            |
|  | MillerDrive™                                                                      | SuperFET®                                                                         |  |
| Fairchild®                                                                        | MotionMax™                                                                        | SuperSOT™-3                                                                       | UHC®                                                                                |
| Fairchild Semiconductor®                                                          | Motion-SPM™                                                                       | SuperSOT™-6                                                                       | Ultra FRFET™                                                                        |
| FACT Quiet Series™                                                                | mW Saver™                                                                         | SuperSOT™-8                                                                       | UniFET™                                                                             |
| FACT®                                                                             | OptoHiT™                                                                          | SupreMOS®                                                                         | VCX™                                                                                |
| FAST®                                                                             | OPTOLOGIC®                                                                        | SyncFET™                                                                          | VisualMax™                                                                          |
| FastVCore™                                                                        | OPTOPLANAR®                                                                       | Sync-Lock™                                                                        | XS™                                                                                 |
| FETBench™                                                                         |  |  |                                                                                     |
| FlashWriter®                                                                      | PDP SPM™                                                                          |                                                                                   |                                                                                     |

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- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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# PRODUCT STATUS DEFINITIONS

## Definition of Terms

| Datasheet Identification | Product Status        | Definition                                                                                                                                                                                          |
|--------------------------|-----------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Advance Information      | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.                                                                       |
| Preliminary              | First Production      | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
| No Identification Needed | Full Production       | Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.                                               |
| Obsolete                 | Not In Production     | Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.                                                    |

Rev. I54



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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